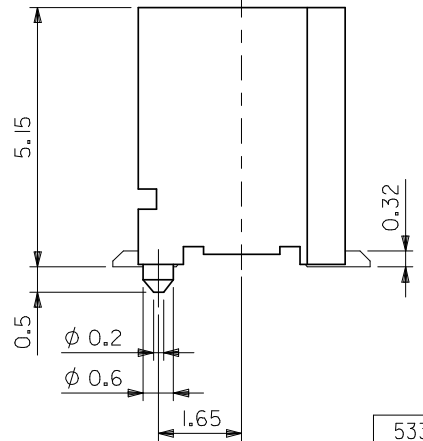


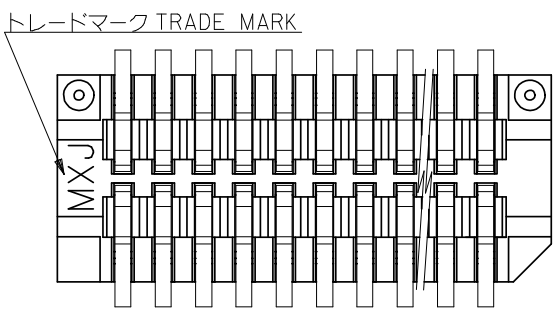
注記 NOTES

1. 嵌合相手 : 52465 シリーズ
MATES WITH : 52465 SERIES
2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
3. 本製品は 53364-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**17



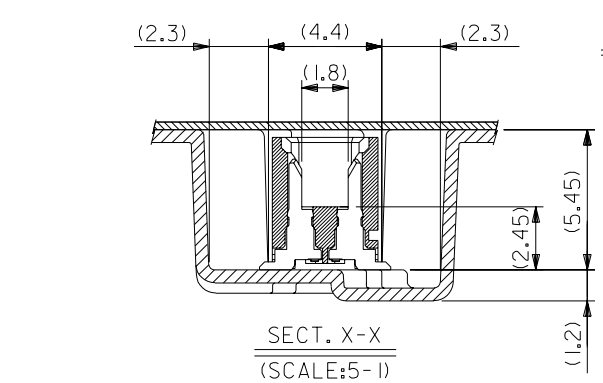
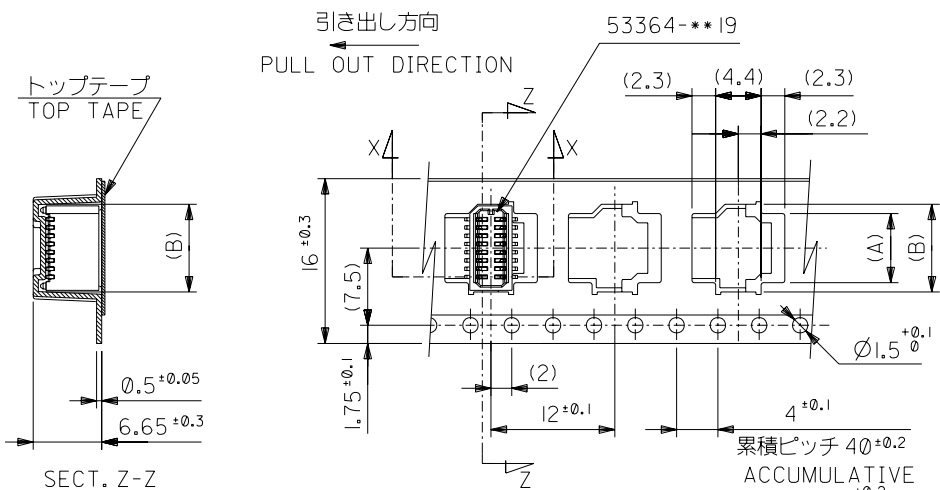
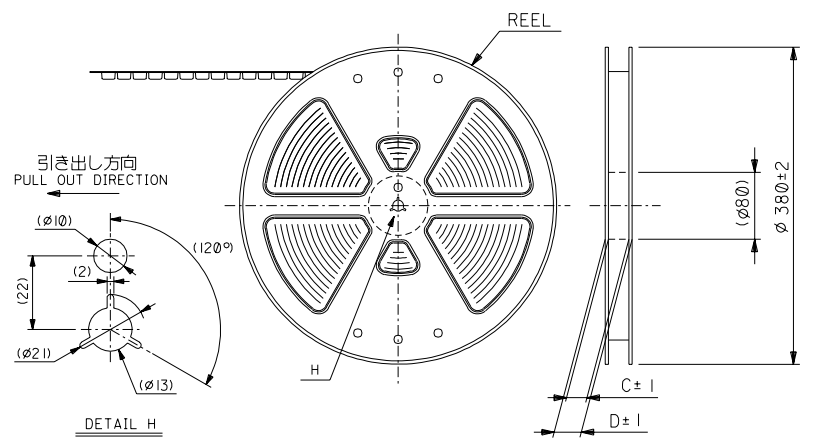
53364-**19
MODEL NO.

17.0	0.4	17.8	16.9	15.2	53364-4019	40
15.4	0.4	16.2	15.3	13.6	53364-3619	36
13.0	0.8	13.8	12.9	11.2	53364-3019	30
12.2	0.4	13.0	12.1	10.4	53364-2819	28
9.0	0.4	9.8	8.9	7.2	53364-2019	20
8.2	0.8	9.0	8.1	6.4	53364-1819	18
5.8	0.4	6.6	5.7	4.0	53364-1219	12
5.0	0.8	5.8	4.9	3.2	53364-1019	10
E	D	C	B	A	MATERIAL NO.	極数 CKT.



REVISED EC NO: J2008-3931 DRWN: MAKURAA 2008/05/26 CHKD: T. HARIYAMA 2008/05/26 APPR: NUKITA 2008/08/21	DESCRIPTION 10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3 ANGULAR $\pm 3^\circ$ DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION			
		DRAWN BY M. NABEI		DATE TITLE 0.8 BOARD TO BOARD CONN. WAFER ASS ST.SMT -LEAD FREE-		CHECKED BY K. TOJO		DATE MOLEX INCORPORATED		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 1	
		APPROVED BY M. SASAO		DATE DOCUMENT NO. SD-53364-001		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
		REV A		EN-02JA(021)									

DWG. NO. SD-53364-002
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING

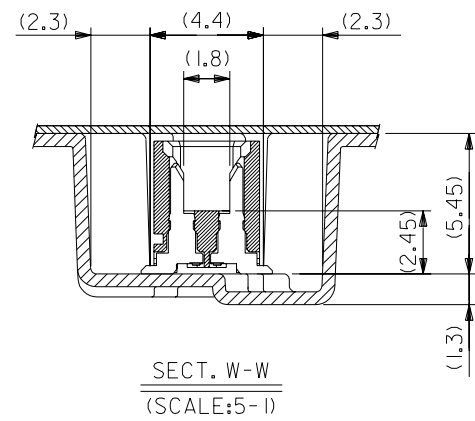
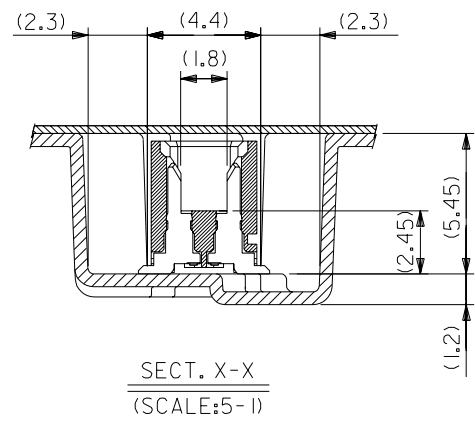
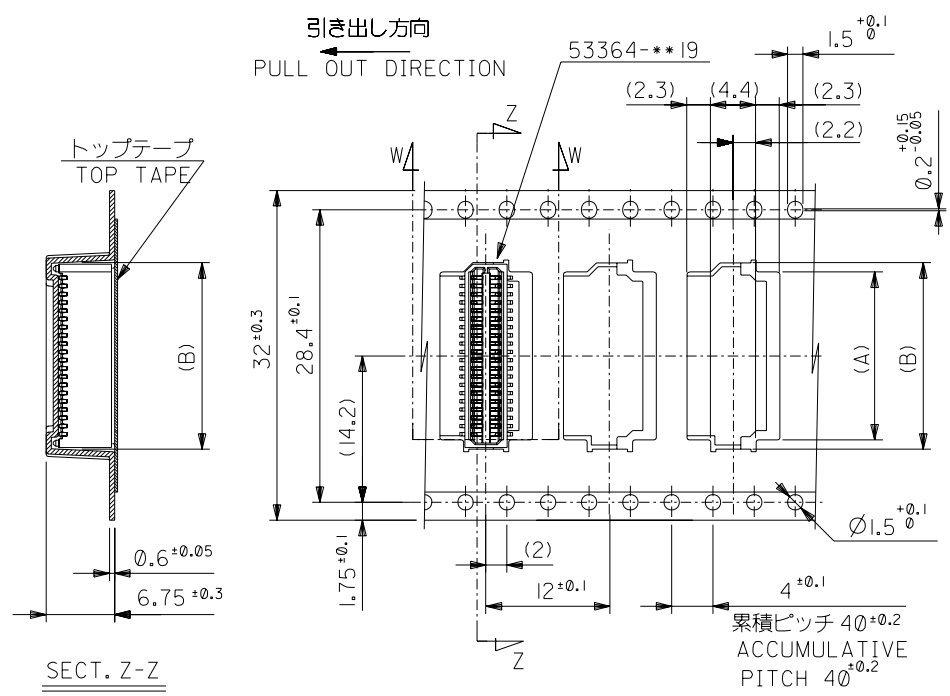
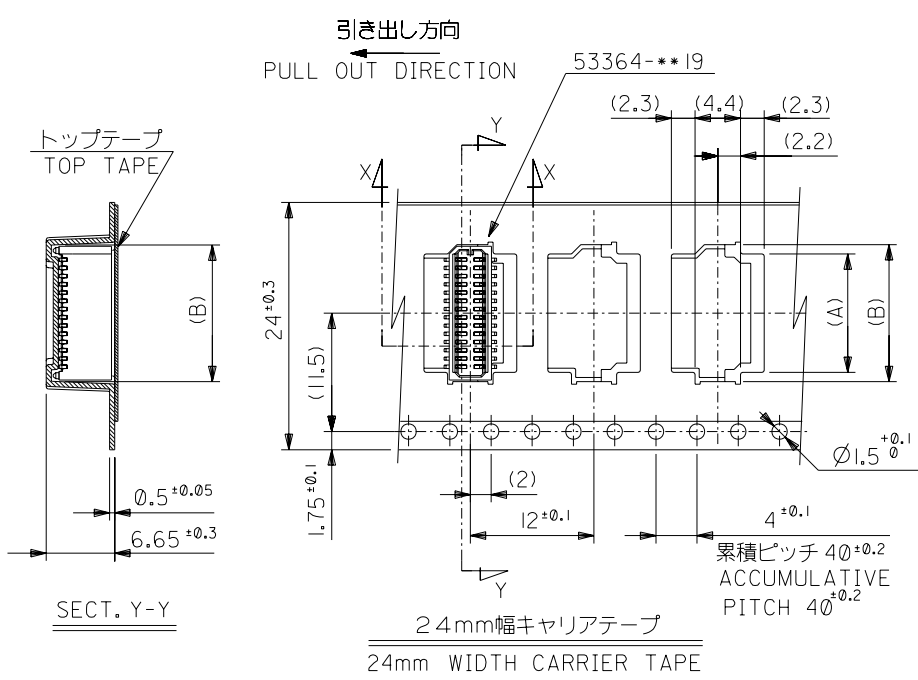


注記 NOTES

- 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
 トップテープ TOP TAPE トップテープ TOP TAPE
 リーダー部 LEADER PART 未接着部 NON-BONDED PART
 175 ±25 25 ±5
 引き出し方向 PULL OUT DIRECTION
 リーダー部 (空部) LEADER PART (EMPTY) 120 ±20
 部品挿入部 COMPONENT SUPPLIER
 末端部 (空部) TAIL PART (EMPTY) 150 ±40
 引き出し方向 PULL OUT DIRECTION
- トップテープの剥離強度：(剥離方向は下図参照)
 0.1~1.3N (10~130gf) 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)
 PEELING OFF FORCE OF TOP TAPE
 0.1~1.3N (10~130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION
 引き出し方向 PULL OUT DIRECTION 剥離方向 PEEL OFF DIRECTION
 10°
- 材料 MATERIAL
 キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE
 トップテープ：PET, PE, PEF TOP TAPE:PET,PE,PEF
 リール：ポリスチレン (PS) REEL:POLYSTYRENE(PS)
 <リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>
- 本製品は 53364-**-90 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 53364-**-90

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 30 未満 UNDER	±0.25
未満 10 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

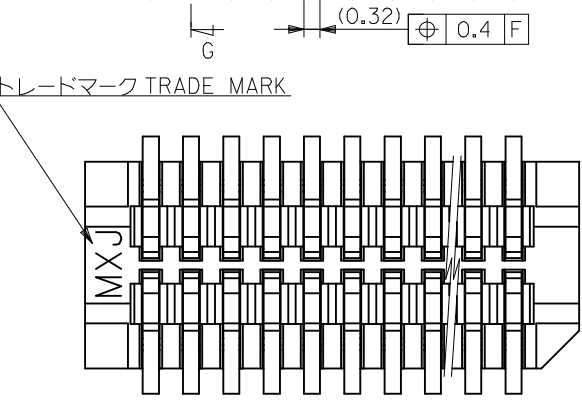
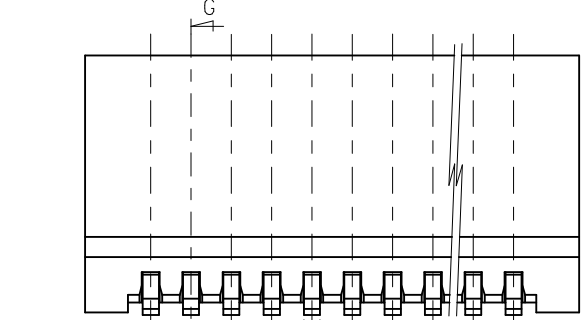
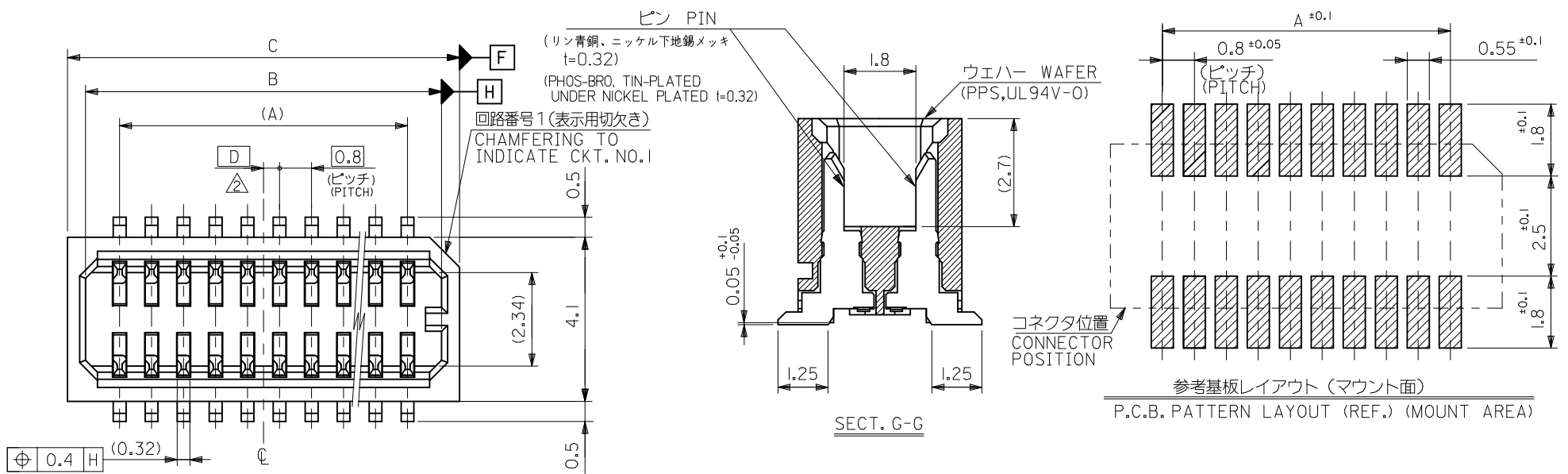
53364-**-70 MODEL NO.	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT	
		16	21.4	17.4	9.3 6.9 6.1	7.5 5.1 4.3	53364-1870 53364-1270 53364-1070	18 12 10
材料 MATERIAL 注記参照 SEE NOTES						molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社		
仕上げ FINISH						— # —		REVISE ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE						— # —		TITLE 名称
被覆外径 INS. RANGE						— # —		0.8 BtB Conn Wafer Assy ST SMT With Boss Embstp Pkg -LEAD FREE-
0 新規作成 RELEASED (1/2004-2950)	M.N. M.S	04/03/09	04/03/09	DRAWN BY M.NABEI	CHK'D BY K.TOJO	DWG. NO. (SHEET 1 OF 2) REV 0		
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	APP'D BY M.SASAO	尺度 SCALE	SD-53364-002		



32	37.4	33.4	18.1	16.3	53364-4070	40
24	29.4	25.4	16.5	14.7	53364-3670	36
			14.1	12.3	53364-3070	30
			13.3	11.5	53364-2870	28
			10.1	8.3	53364-2070	20

53364-***70	キャリアテープ幅	D	C	(B)	(A)	MATERIAL NO.	極数	
MODEL NO.	CARRIER TAPE WIDTH						CIRCUIT	
	材料	MATERIAL					MOLLEX MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
	仕上げ	FINISH						
	適用電線範囲	WIRE RANGE					REVISE ONLY ON CAD SYSTEM	
	被覆外径	INS. RANGE					TITLE 名称	
	記号	0	新規作成 (J2004-2958)	M.N.	04/03/09	0.8 BtB Conn Wafer Assy ST SMT With Boss Embstp Pkg -LEAD FREE-		
	変更内容	DR.	日付	DR.	日付	DWG. NO. (SHEET 2 OF 2)	REV	
	一般公差	GENERAL TOLERANCES					SD-53364-002	0

10 9 8 7 6 5 4 3 2 1



注記 NOTES

1. 嵌合相手 : 52465,52588 シリーズ
MATES WITH : 52465,52588 SERIES
2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
3. 本製品は 53364-**-27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**-27.

0.4	16.2	15.3	13.6	53364-3629	36
0.8	13.8	12.9	11.2	53364-3029	30
0.4	9.8	8.9	7.2	53364-2029	20
0.8	9.0	8.1	6.4	53364-1829	18
D	C	B	A	MATERIAL. NO.	極数 CKT.

REVISED EC NO: J2016-1237 DRWN: MISHIKAWA CHKD: Y0110 APPR: Y0110	DESCRIPTION 2016/06/07 2016/06/07 2016/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		DESIGN UNITS		TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST.SMT -LEAD FREE- molex DOCUMENT NO. SD-53364-003 SHEET NO. 1 OF 2	
		MM ONLY		10:1		METRIC		THIRD ANGLE PROJECTION			
		0.25 UNDER	UNDER	±0.2	DRAWN BY	DATE	M. NABEI		'04/03/09		
		0.25 OVER	0.5 UNDER	±0.2	CHECKED BY	DATE	K. TOJO		'04/03/09		
0.5 OVER	1.0 UNDER	±0.2	APPROVED BY	DATE	M. SASAO		'04/03/09				
1.0 OVER	10 UNDER	±---	MATERIAL NO.		SEE CHART						
10 OVER	30 UNDER	±---	ANGULAR		±1 °						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
		A3									

9 8 7 6 5 4 3 2 1